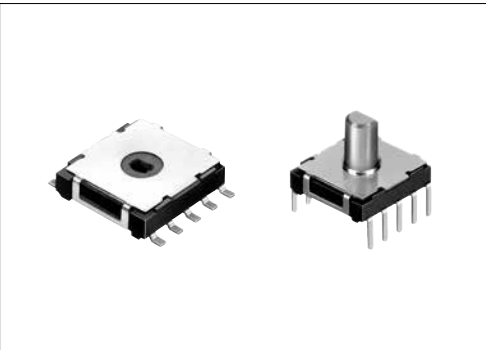


Single-unit and dual-unit types suit a variety of controls



Typical Specifications

Items		Specifications
Rating (max.)/(min.) (Resistive load)		0.1A 16V DC / 50μA 3V DC
Contact resistance (Initial / After operating life)		50mΩ max. / 100mΩ max.
Rotational torque		6±3mN·m / 13±5mN·m
Total rotational angle	Without load	10,000 cycles
	With load	10,000 cycles (0.1A 16V DC)

Product Line

Poles	Positions	Changeover angle	Changeover timing	Rotational torque	Actuator configuration	Soldering	Actuator length (mm)	Minimum order unit (pcs.)		Product No.	Drawing No.
								Japan	Export		
1	9	40±3°	Non shorting	6±3mN·m	Flat	Insertion	5.8	1,215	4,860	SRBQ090200	1
				13±5mN·m						SRBQ490100	2
				6±3mN·m	Non shaft	Reflow	—	1,200	4,800	SRBQ290301	3

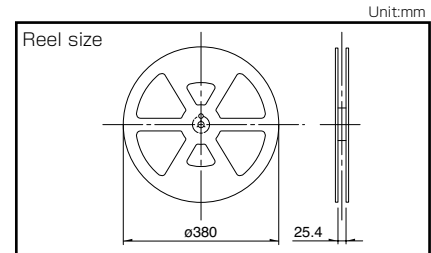
Packing Specifications

Taping

Series	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing		
SRBQ290301	1,200	2,400	4,800	24	406×406×190

Tray

Series	Number of packages (pcs.)		Export package measurements (mm)
	1 case /Japan	1 case /export packing	
SRBQ090200 SRBQ490100	1,215	4,860	540×360×290



■ Dimensions

Insertion Type

Unit:mm

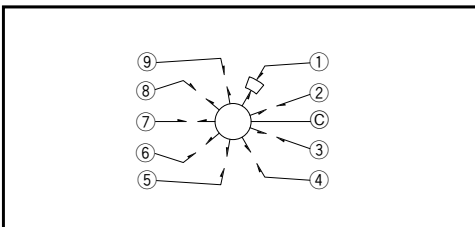
No.	Style	PC board mounting hole dimensions (Viewed from direction A)
1	<p>Standard torque</p>	<p>10-$\phi 1$ hole</p>
2	<p>Heavy torque</p>	

Reflow Type

Unit:mm

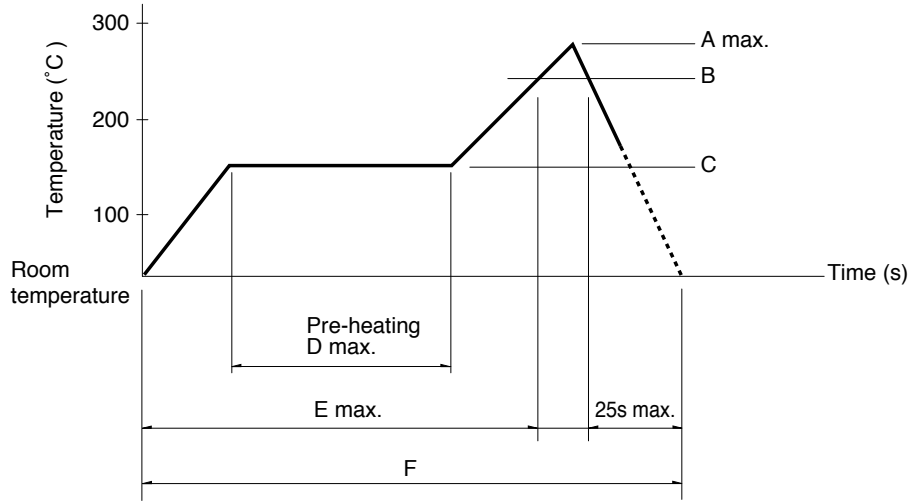
No.	Style	PC board mounting hole and land dimensions (Viewed from direction A)
3		<p>4-$\phi 0.9$ hole</p> <p>Pattern section</p>

■ Circuit Diagram (Viewed from Direction A)

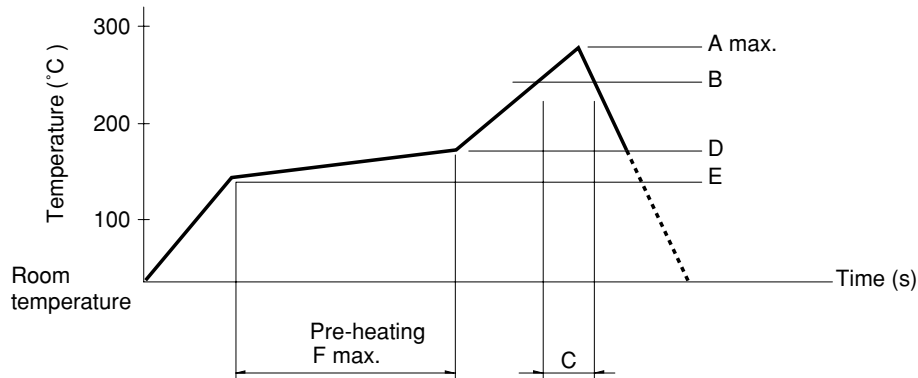


■ Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple $\phi 0.1$ to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (°C)	D (s)	E (s)	F (s)
SRBQ	250	200	150±5	80 to 100	—	—



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SRBD	260	230	40	180	150	120

- Notes**
1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

■ Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SRBQ, SRBM, SRBV, SRRM, SRRN	350±10°C	3+1/0s
SRBQ (Reflow type)	350±5°C	3s max.

■ Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SRBM	100°C max.	60s max.	260±5°C	5s max.
SRBV, SRRM, SRRN	—	—	260±5°C	10±1s
SRBQ	—	—	260±5°C	5±1s